

Title (en)  
AN ELECTRONIC ASSEMBLY AND A METHOD FOR MANUFACTURING THE SAME

Title (de)  
ELEKTRONISCHE BAUGRUPPE UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)  
ENSEMBLE ELECTRONIQUE ET PROCEDE DE FABRICATION DE CE DERNIER

Publication  
**EP 1459610 A1 20040922 (EN)**

Application  
**EP 02793728 A 20021219**

Priority  
• SE 0202429 W 20021219  
• SE 0104335 A 20011219

Abstract (en)  
[origin: WO03053115A1] An electronic assembly and a method of manufacturing such an assembly in which a carrier 13 for electronic components 14 and leads 18 for external connection are connected with each other by interconnections 19 including solder joints 22. In order to sustain heating periods, at least one of said interconnections comprises an adhesive joint 23 in addition to the solder joint applied between the carrier and one lead.  
[origin: WO03053115A1] An electronic assembly and a method of manufacturing such an assembly in which a carrier (13) for electronic components (14) and leads (18) for external connection are connected with each other by interconnections (19) including solder joints (22). In order to sustain heating periods, at least one of said interconnections comprises an adhesive joint (23) in addition to the solder joint applied between the carrier and one lead.

IPC 1-7  
**H05K 3/34**; H05K 3/36; H05K 13/04; H01R 4/02

IPC 8 full level  
**H05K 3/34** (2006.01); H01R 4/02 (2006.01); H01R 43/02 (2006.01); H05K 3/30 (2006.01)

CPC (source: EP)  
**H05K 3/3405** (2013.01); H01L 2224/16225 (2013.01); H01L 2924/19105 (2013.01); H01L 2924/19106 (2013.01); H01R 4/027 (2013.01); H01R 12/57 (2013.01); H01R 43/0263 (2013.01); H05K 3/305 (2013.01); H05K 3/3421 (2013.01); H05K 2201/1034 (2013.01)

Citation (search report)  
See references of WO 03053115A1

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SI SK TR

DOCDB simple family (publication)  
**WO 03053115 A1 20030626**; AU 2002359207 A1 20030630; CN 1608397 A 20050420; EP 1459610 A1 20040922; SE 0104335 D0 20011219; TW 540264 B 20030701

DOCDB simple family (application)  
**SE 0202429 W 20021219**; AU 2002359207 A 20021219; CN 02825851 A 20021219; EP 02793728 A 20021219; SE 0104335 A 20011219; TW 91108427 A 20020424